

### ABSTRACT

A method and apparatus for rinsing and drying a substrate (100) of a semiconductor wafer (102), has a first nozzle (110) dispensing rinsing fluid against the substrate (100); and a second nozzle (114) dispensing dry gas under pressure against the substrate (100) during a drying cycle to dry the substrate (100) completely. The second nozzle (114) can point to the substrate (100) while the substrate (100) spins. The nozzles (110) and (114) can be positioned by a robot arm (112).